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	ENTRY	SESSION
FULL ESTIMATED COST	0.21	0.21

FILE 'EUROPATFULL' ENTERED AT 13:50:37 ON 15 APR 2003
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FILE 'USPAT2' ENTERED AT 13:50:37 ON 15 APR 2003
CA INDEXING COPYRIGHT (C) 2003 AMERICAN CHEMICAL SOCIETY (ACS)

=> s Saito, Noriaki/in
L1 48 SAITO, NORIAKI/IN

=> s novolak resin# and formaldehyde3 and (phenol or ortho-cresol or 0-cresol)
3 FILES SEARCHED...
L2 0 NOVOLAK RESIN# AND FORMALDEHYDE3 AND (PHENOL OR ORTHO-CRESOL OR 0-CRESOL)

=> s novolak resin# and formaldehyde and (phenol or ortho-cresol or o-cresol)
L3 4266 NOVOLAK RESIN# AND FORMALDEHYDE AND (PHENOL OR ORTHO-CRESOL OR O-CRESOL)

=> s l3 and oxalic acid catalyst#
L4 48 L3 AND OXALIC ACID CATALYST#

=> s l4 and temperature# and pressure
L5 17 L4 AND TEMPERATURE# AND PRESSURE

=> s l5 and ortho ratio
L6 1 L5 AND ORTHO RATIO

=> d

L6 ANSWER 1 OF 1 USPATFULL

Full Text	Citing References
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AN 2002:172464 USPATFULL
TI Method of producing **novolak resin**
IN Saito, Noriaki, Toyonaka-shi, JAPAN
Aizu, Ichishi, Niihama-shi, JAPAN
Nakajima, Nobuyuki, Niihama-shi, JAPAN
Fujiwara, Masahiro, Niihama-shi, JAPAN
Yano, Koji, Niihama-shi, JAPAN
PA SUMITOMO CHEMICAL COMPANY, LIMITED (non-U.S. corporation)
PI US 2002091224 A1 20020711
AI US 2001-364 A1 20011204 (10)
PRAI JP 2000-377258 20001212
JP 2000-377259 20001212
JP 2001-153632 20010523
DT Utility
FS APPLICATION
LN.CNT 579
INCL INCLM: 528/129.000
NCL NCLM: 528/129.000
IC [7]

ICM: C08G008-04
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

=> d 15 1-17

L5 ANSWER 1 OF 17 EUROPATFULL COPYRIGHT 2003 WILA

Full
Text

PATENT APPLICATION - PATENTANMELDUNG - DEMANDE DE BREVET

AN 342035 EUROPATFULL ED 20000917 EW 198946 FS OS STA B
TIEN Powdered epoxy resin compositions.
TIDE Pulverfoermige Epoxydharzzusammensetzungen.
TIFR Compositions de resines epoxydes sous forme de poudre.
IN Bymark, Richard M. c/o Minnesota Mining and, Manufacturing Company 3M
Austin Center, P.O. Box 2963 Austin Texas 78769-2963, US;
Kirk, Alan R. c/o Minnesota Mining and, Manufacturing Company 2501
Hudson Road P.O.Box, 33427 St. Paul, Minnesota 55133-3427, US;
Griggs, Allen L. c/o Minnesota Mining and, Manufacturing Company 2501
Hudson Road P.O.Box, 33427 St. Paul Minnesota 55133-3427, US;
Martin, Steven J. c/o Minnesota Mining and, Manufacturing Company 2501
Hudson Road P.O. Box, 33427 St. Paul, Minnesota 55133-3427, US
PA MINNESOTA MINING AND MANUFACTURING COMPANY, P.O. Box 33427, St. Paul
Minnesota 55133-3427, US
SO Wila-EPZ-1989-H46-T1
DS R DE; R FR; R GB; R IT
PIT EPA2 EUROPAEISCHE PATENTANMELDUNG
PI EP 342035 A2 19891115
OD 19891115
AI EP 1989-304781 19890511
PRAI US 1988-193498 19880512
IC ICM C08G059-62
ICS C09D003-58 C09D005-00

L5 ANSWER 2 OF 17 PCTFULL COPYRIGHT 2003 Univentio

Full
Text

AN 2002031011 PCTFULL ED 20020515 EW 200216
TIEN FRACTIONATION OF RESINS USING A STATIC MIXER AND A LIQUID-LIQUID
CENTRIFUGE
TIFR FRACTIONNEMENT DE RESINES AU MOYEN D'UN MELANGEUR FIXE ET D'UNE
CENTRIFUGEUSE LIQUIDE-LIQUIDE
IN WANAT, Stanley, F., 3 Frances Lane, Scotch Plains, NJ 07076, US;
RAHMAN, M., Dalil, 62 Concord Ridge Road, Flemington, NJ 08822, US;
XIANG, Zhong, 1142 Easton Avenue, Apartment G, Somerset, NJ 08873, US
PA CLARIANT INTERNATIONAL LTD, Rothausstrasse 61, CH-4132 Muttensz, CH [CH,
CH], for JP only;
CLARIANT FINANCE (BVI) LIMITED, Wickhams Cay, P.O. Box 662, Road Town,
Tortola, VG [-, -], for all designates States except JP
AG HUETTER, Klaus, Clariant Service GmbH, Patente, Marken, Lizenzen, Am
Unisys-Park 1, 65843 Sulzbach, DE
LAF English
LA English
DT Patent
PI WO 2002031011 A2 20020418
DS W: CN JP KR SG
RW (EPO): AT BE CH CY DE DK ES FI FR GB GR IE IT LU MC NL PT SE TR
AI WO 2001-EP11357 A 20011002
PRAI US 2000-09/687,137 20001013
US 2000-09/698,724 20001027
ICM C08G008-00
ICS B01D017-038; G03F007-023

L5 ANSWER 3 OF 17 PCTFULL COPYRIGHT 2003 Univentio

Full
Text

AN 2000033137 PCTFULL ED 20020515
 TIEN PREPARATION OF FRACTIONATED **NOVOLAK RESINS** BY A NOVEL EXTRACTION
 TECHNIQUE
 TIFR NOUVELLE TECHNIQUE D'EXTRACTION POUR LA PREPARATION DE RESINES NOVOLAQUE
 FRACTIONNEES
 IN WANAT, Stanley, F.;
 RAHMAN, Dalil, M.;
 KOKOSZKA, John, J.;
 NARASIMHAN, Balaji
 PA CLARIANT INTERNATIONAL LTD.
 LA English
 DT Patent
 PI WO 2000033137 A2 20000608
 DS W: CN JP KR SG AT BE CH CY DE DK ES FI FR GB GR IE IT LU MC NL
 PT SE
 AI WO 1999-EP8391 A 19991103
 PRAI US 1998-09/190,763 19981112
 ICM G03F007-023
 ICS C08G008-08

L5 ANSWER 4 OF 17 PCTFULL COPYRIGHT 2003 Univentio

Full
Text

AN 1999031157 PCTFULL ED 20020515
 TIEN FRACTIONATED **NOVOLAK RESIN** AND PHOTORESIST COMPOSITION THEREFROM
 TIFR RESINE NOVOLAK FRACTIONNEE ET COMPOSITION DE RESINE PHOTOSENSIBLE
 QU'ELLE PERMET D'OBTENIR
 IN RAHMAN, M., Dalil;
 COOK, Michelle, M.;
 LU, Ping-Hung
 PA CLARIANT INTERNATIONAL, LTD.
 LA English
 DT Patent
 PI WO 9931157 A1 19990624
 DS W: CN JP KR SG AT BE CH CY DE DK ES FI FR GB GR IE IT LU MC NL
 PT SE
 AI WO 1998-EP7754 A 19981201
 PRAI US 1997-08/991,034 19971215
 ICM C08G008-08
 ICS G03F007-023

L5 ANSWER 5 OF 17 USPATFULL

Full
Text

Citing
References

AN 2003:92961 USPATFULL
 TI Negative photoresist compositions for the formation of thick films,
 photoresist films and methods of forming bumps using the same
 IN Saito, Koji, Kanagawa, JAPAN
 Misumi, Kouichi, Kanagawa, JAPAN
 Okui, Toshiki, Kanagawa, JAPAN
 Komano, Hiroshi, Kanagawa, JAPAN
 PA TOKYO OHKA KOGYO CO., LTD. (non-U.S. corporation)
 PI US 2003064319 A1 20030403
 AI US 2002-147984 A1 20020520 (10)
 PRAI JP 2001-151131 20010521
 DT Utility
 FS APPLICATION
 LN.CNT 903
 INCL INCLM: 430/270.100
 INCLS: 430/325.000

NCL NCLM: 430/270.100
NCLS: 430/325.000
IC [7]
ICM: G03F007-038

L5 ANSWER 6 OF 17 USPATFULL

Full Text	Citing References
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AN 2003:86101 USPATFULL
TI Positive photoresist composition for the formation of thick films, photoresist film and method of forming bumps using the same
IN Misumi, Kouichi, Kanagawa, JAPAN
Saito, Koji, Kanagawa, JAPAN
Okui, Toshiki, Kanagawa, JAPAN
Komano, Hiroshi, Kanagawa, JAPAN
PA TOKYO OHKA KOGYO CO., LTD. (non-U.S. corporation)
PI US 2003059706 A1 20030327
AI US 2002-90170 A1 20020305 (10)
PRAI JP 2001-61565 20010306
DT Utility
FS APPLICATION
LN.CNT 867
INCL INCLM: 430/190.000
INCLS: 430/189.000; 430/193.000
NCL NCLM: 430/190.000
NCLS: 430/189.000; 430/193.000
IC [7]
ICM: G03C001-52
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 7 OF 17 USPATFULL

Full Text	Citing References
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AN 2003:26414 USPATFULL
TI Fractionation of resins using a static mixer and a liquid-liquid centrifuge
IN Wanat, Stanley F., Scotch Plains, NJ, United States
Rahman, M. Dalil, Flemington, NJ, United States
Xiang, Zhong, Somerset, NJ, United States
PA Clariant Finance (BVI) Limited, VIRGIN ISLANDS (BRITISH) (non-U.S. corporation)
PI US 6512087 B1 20030128
AI US 2000-698724 20001027 (9)
RLI Continuation-in-part of Ser. No. US 2000-687137, filed on 13 Oct 2000
DT Utility
FS GRANTED
LN.CNT 947
INCL INCLM: 528/502.000D
INCLS: 528/129.000; 528/148.000; 430/192.000; 430/193.000; 210/634.000
NCL NCLM: 528/502.000D
NCLS: 210/634.000; 430/192.000; 430/193.000; 528/129.000; 528/148.000
IC [7]
ICM: C08F006-04
ICS: G03F007-023
EXF 430/270-1; 430/192; 430/193; 430/325; 430/326; 430/330; 528/148; 528/129; 528/502D; 210/634
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 8 OF 17 USPATFULL

Full Text	Citing References
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AN 2002:172464 USPATFULL
TI Method of producing **novolak resin**
IN Saito, Noriaki, Toyonaka-shi, JAPAN

Aizu, Ichishi, Niihama-shi, JAPAN
Nakajima, Nobuyuki, Niihama-shi, JAPAN
Fujiwara, Masahiro, Niihama-shi, JAPAN
Yano, Koji, Niihama-shi, JAPAN

PA SUMITOMO CHEMICAL COMPANY, LIMITED (non-U.S. corporation)

PI US 2002091224 A1 20020711

AI US 2001-364 A1 20011204 (10)

PRAI JP 2000-377258 20001212

JP 2000-377259 20001212

JP 2001-153632 20010523

DT Utility

FS APPLICATION

LN.CNT 579

INCL INCLM: 528/129.000

NCL NCLM: 528/129.000

IC [7]

ICM: C08G008-04

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 9 OF 17 USPATFULL

Full Text	Citing References
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AN 2000:125188 USPATFULL

TI Preparation of fractionated **novolak resins** by a novel extraction technique

IN Wanat, Stanley F., Scotch Plains, NJ, United States

Rahman, M. Dalil, Somerville, NJ, United States

Kokoszka, John J., Warwick, RI, United States

Narasimhan, Balaji, Highland Park, NJ, United States

PA Clariant Finance (BVI) Limited, Virgin Islands (British) (non-U.S. corporation)

PI US 6121412 20000919

AI US 1999-418239 19991014 (9)

RLI Continuation-in-part of Ser. No. US 1998-190763, filed on 12 Nov 1998, now abandoned

DT Utility

FS Granted

LN.CNT 1037

INCL INCLM: 528/502.000D

INCLS: 528/129.000; 528/144.000; 528/491.000; 430/270.100; 438/455.000; 438/689.000; 427/352.000; 427/372.200; 210/634.000

NCL NCLM: 528/502.000D

NCLS: 210/634.000; 427/352.000; 427/372.200; 430/270.100; 438/455.000; 438/689.000; 528/129.000; 528/144.000; 528/491.000

IC [7]

ICM: C08F006-04

ICS: C08F006-22; C08G014-04

EXF 528/502D; 528/129; 528/144; 528/491; 430/270.1; 427/352; 427/372.2; 210/634; 438/455; 438/689

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 10 OF 17 USPATFULL

Full Text	Citing References
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AN 2000:40811 USPATFULL

TI Fractionated **novolak resin** and photoresist composition therefrom

IN Rahman, M. Dalil, Flemington, NJ, United States

Cook, Michelle, Somerville, NJ, United States

Lu, Ping-Hung, Bridgewater, NJ, United States

PA Clariant Finance (BVI) Limited, Virgin Islands (British) (non-U.S. corporation)

PI US 6045966 20000404

AI US 1997-991034 19971215 (8)

DT Utility

FS Granted
 LN.CNT 964
 INCL INCLM: 430/270.100
 INCLS: 430/311.000; 528/155.000; 528/165.000
 NCL NCLM: 430/270.100
 NCLS: 430/311.000; 528/155.000; 528/165.000
 IC [7]
 ICM: G03C005-00
 EXF 528/155; 528/165; 430/270.1; 430/311
 CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 11 OF 17 USPATFULL

Full Text	Citing References
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AN 97:123007 USPATFULL
 TI Positive photoresist coating solution comprising a mixed solvent of
 propylene glycol monopropyl ether and 2-heptanone
 IN Ohno, Hayato, Kanagawa, Japan
 Nakao, Taku, Kanagawa, Japan
 Harada, Hisanobu, Kanagawa, Japan
 Hidesaka, Shinichi, Kanagawa, Japan
 Kohara, Hidekatsu, Kanagawa, Japan
 Nakayama, Toshimasa, Kanagawa, Japan
 PA Tokyo Ohka Kogyo Co., LTD., Kanagawa, Japan (non-U.S. corporation)
 PI US 5702862 19971230
 AI US 1997-797663 19970131 (8)
 PRAI JP 1996-40461 19960202
 DT Utility
 FS Granted
 LN.CNT 481
 INCL INCLM: 430/191.000
 INCLS: 430/192.000; 430/193.000
 NCL NCLM: 430/191.000
 NCLS: 430/192.000; 430/193.000
 IC [6]
 ICM: G03F007-023
 EXF 430/191; 430/192; 430/193
 CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 12 OF 17 USPATFULL

Full Text	Citing References
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AN 86:52384 USPATFULL
 TI Aromatic carboxylic acid and metal-modified phenolic resins and methods
 of preparation
 IN Ginter, James W., Cheektowaga, NY, United States
 Thorpe, Donald H., Williamsville, NY, United States
 Cooke, Victor F. G., Youngstown, NY, United States
 PA Occidental Chemical Corporation, Niagara Falls, NY, United States (U.S.
 corporation)
 PI US 4612254 19860916
 AI US 1985-709461 19850307 (6)
 DT Utility
 FS Granted
 LN.CNT 1586
 INCL INCLM: 428/531.000
 INCLS: 346/210.000; 346/211.000; 346/212.000; 346/216.000; 346/217.000;
 346/225.000; 428/327.000; 428/326.000; 524/509.000; 524/510.000;
 524/595.000; 524/596.000; 525/506.000; 525/508.000; 528/139.000;
 528/140.000; 528/144.000; 528/146.000; 528/147.000; 528/148.000
 NCL NCLM: 503/210.000
 NCLS: 428/326.000; 428/327.000; 503/211.000; 503/212.000; 503/216.000;
 503/217.000; 503/225.000; 524/509.000; 524/510.000; 524/595.000;
 524/596.000; 525/506.000; 525/508.000; 528/139.000; 528/140.000;

528/144.000; 528/146.000; 528/147.000; 528/148.000

IC [4]
 ICM: C08G008-32
 ICS: C08L061-14
 EXF 525/506; 525/508; 528/148; 528/139; 528/140; 528/144; 528/146; 528/147;
 524/596; 524/509; 524/510; 524/595; 346/210; 346/211; 346/212; 346/216;
 346/217; 346/225; 428/327; 428/326; 428/531
 CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 13 OF 17 USPATFULL

Full Text	Citing References
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AN 82:27450 USPATFULL
 TI Catechol resins for the shell process
 IN Craig, Robert S., Hoffman Estates, IL, United States
 PA Acme Resin Corporation, Englewood Cliffs, NJ, United States (U.S. corporation)
 PI US 4333513 19820608
 AI US 1981-240641 19810305 (6)
 RLI Division of Ser. No. US 1979-90388, filed on 1 Nov 1979, now patented, Pat. No. US 4281090, issued on 8 Jul 1981 which is a division of Ser. No. US 1978-869407, filed on 16 Jan 1978, now patented, Pat. No. US 4206262, issued on 3 Jun 1980
 DT Utility
 FS Granted
 LN.CNT 296
 INCL INCLM: 164/526.000
 INCLS: 264/220.000; 264/221.000
 NCL NCLM: 164/526.000
 NCLS: 264/220.000; 264/221.000
 IC [3]
 ICM: B22C001-22
 EXF 164/526; 264/220; 264/221; 525/501; 260/38
 CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 14 OF 17 USPATFULL

Full Text	Citing References
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AN 81:40957 USPATFULL
 TI Catechol resins for the shell process
 IN Craig, Robert S., Hoffman Estates, IL, United States
 PA Acme Resin Corporation, Forest Park, IL, United States (U.S. corporation)
 PI US 4281090 19810728
 AI US 1979-90388 19791101 (6)
 RLI Division of Ser. No. US 1978-869407, filed on 16 Jan 1978, now patented, Pat. No. US 4206262
 DT Utility
 FS Granted
 LN.CNT 277
 INCL INCLM: 525/501.000
 INCLS: 260/038.000
 NCL NCLM: 525/501.000
 NCLS: 523/145.000; 524/541.000
 IC [3]
 ICM: C08L061-12
 EXF 525/495; 525/501; 528/155; 260/DIG.40; 260/38
 CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 15 OF 17 USPATFULL

Full Text	Citing References
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AN 80:27035 USPATFULL
 TI Catechol resins for the shell process

IN Craig, Robert S., Hoffman Estates, IL, United States
 PA Acme Resin Corporation, Forest Park, IL, United States (U.S. corporation)
 PI US 4206262 19800603
 AI US 1978-869407 19780116 (5)
 DT Utility
 FS Granted
 LN.CNT 290
 INCL INCLM: 428/404.000
 INCLS: 260/038.000; 428/407.000; 164/043.000
 NCL NCLM: 428/404.000
 NCLS: 164/021.000; 164/526.000; 428/407.000; 524/448.000
 IC [2]
 ICM: B32B019-04
 ICS: B32B027-14; B32B027-47
 EXF 428/404; 428/407; 428/403; 428/454; 428/524; 260/38; 260/DIG.40; 427/221
 CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 16 OF 17 USPATFULL

Full Text	Citing References
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AN 78:7183 USPATFULL
 TI Plugging compositions for blast furnace tap holes
 IN Funabiki, Kyohei, Fujieda, Japan
 Tokunaga, Tetsuya, Fujieda, Japan
 PA Sumitomo Durez Company, Ltd., Tokyo, Japan (non-U.S. corporation)
 PI US 4072531 19780207
 AI US 1976-666290 19760312 (5)
 RLI Continuation-in-part of Ser. No. US 1975-639679, filed on 11 Dec 1975, now Defensive Publication No.
 PRAI JP 1975-30669 19750315
 DT Utility
 FS Granted
 LN.CNT 280
 INCL INCLM: 106/056.000
 INCLS: 106/055.000; 106/058.000; 106/065.000; 106/067.000; 260/038.000
 NCL NCLM: 523/140.000
 NCLS: 501/099.000; 501/109.000; 501/127.000; 501/128.000; 501/130.000; 524/594.000
 IC [2]
 ICM: C04B035-02
 ICS: C04B035-66; C04B035-04; C04B035-66
 EXF 106/56; 106/67; 106/65; 106/58; 106/55; 260/38
 CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 17 OF 17 USPATFULL

Full Text	Citing References
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AN 76:42905 USPATFULL
 TI Process for preparing phenolic filaments
 IN Koyama, Hiroaki, Osaka, Japan
 PA Nippon Kynol Inc., Osaka, Japan (non-U.S. corporation)
 PI US 3972959 19760803
 AI US 1974-517029 19741022 (5)
 PRAI JP 1973-119673 19731024
 DT Utility
 FS Granted
 LN.CNT 741
 INCL INCLM: 260/841.000
 INCLS: 008/115.500; 260/054.000; 260/055.000; 260/056.000; 260/059.000R; 260/843.000; 260/847.000; 260/848.000; 264/176.000F; 264/236.000; 264/347.000
 NCL NCLM: 525/429.000
 NCLS: 008/115.560; 264/211.150; 264/211.160; 264/236.000; 264/347.000;

525/160.000; 525/164.000; 525/442.000; 528/493.000; 528/496.000
IC [2]
ICM: D06M013-12
ICS: D06M013-16; D06M013-20
EXF 260/59R; 260/841; 264/177F; 264/176F; 264/236; 264/347; 008/115.5
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

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